L Number	Hits	Search Text	DB	Time stamp
1	54309	(Chemical adj mechanical adj polish\$3) or CMP or planariz\$5	USPAT;	2003/06/20 10:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
36	54		USPAT;	2003/06/20 10:29
"	J		US-PGPUB;	2000,00,20 10.20
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
43	721	((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	USPAT;	2003/06/20 10:27
43	721	1 '' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	US-PGPUB;	2003/00/20 10.27
		density)		
			EPO; JPO;	
1			DERWENT;	
	240	(//Oharriadadisaadadisaadadisadisadisadisadisadi	IBM_TDB	00000000000000
50	316	(((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	USPAT;	2003/06/20 10:27
		density)) and (etch\$3 with pattern)	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
57	42	((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	USPAT;	2003/06/20 10:28
ļ		density)) and (etch\$3 with pattern)) and (thickness with variation\$1)	US-PGPUB;	
!			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
64	54	((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	USPAT;	2003/06/20 10:29
		density)) and (etch\$3 with pattern)) and (device near3 region\$1)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
71	91	(((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	USPAT;	2003/06/20 10:29
		density)) and (etch\$3 with pattern)) and (thickness with variation\$1)) or ((((US-PGPUB;	
		(Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	EP0; JP0;	
		density)) and (etch\$3 with pattern)) and (device near3 region\$1))	DERWENT;	
			IBM_TDB	
85	7	((((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	USPAT;	2003/06/20 10:45
		density)) and (etch\$3 with pattern)) and (thickness with variation\$1)) or ((((US-PGPUB;	
		(Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	EPO; JPO;	
		density)) and (etch\$3 with pattern)) and (device near3 region\$1))) and (test\$3	DERWENT;	
		with region\$1)	IBM_TDB	
92	84	((((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	USPAT;	2003/06/20 10:46
		density)) and (etch\$3 with pattern)) and (thickness with variation\$1)) or ((((US-PGPUB;	
		(Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	EPO; JPO;	
		density)) and (etch\$3 with pattern)) and (device near3 region\$1))) not ((((((DERWENT;	
		(Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3	IBM_TDB	
		density)) and (etch\$3 with pattern)) and (thickness with variation\$1)) or ((((
		(Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3		
		density)) and (etch\$3 with pattern)) and (device near3 region\$1))) and (test\$3		
		with region\$1))		1
		,	1	l